DES Machine

Hyper Etching

UCE is devoted to innovating cutting edge technology of PCB wet-processing equipment to meet the requirements of industry development.

Capability

Panel Size(FPC):	500mmWxSOOmm L(max) 250mmWx250mm L(min) 0.025mm(core) +12/12μm Cu~1.2mm
Panel Size (Rigid Board):	630mmWx 630mml(max) 355mmWx 355mml(min) 0.025mm(core) +12/12μm Cu~3.2mm
Panel Size (Back Panel):	1OSOmmWx 11 OOmmL(max) 355mmWx 355mml(min) 0.5~12mm

Specification and capability are subject to contract, and machine should work with proper chemicals.

Hyper Etching Advantages

1. Suitable for fine line circuit
2. Suitable for thick copper etching
3. Enhance etching factor

Collaboration with Vacuum Etching and Specialized Spray

Specialized Original

Small Size Particle

Up side Nozzle

Vacuum Nozzle

Small Size Particle of Etching Chemicals and Vacuum Etching are More Easy to Enter Between DFR.

L/5=30/30
12μm Cu, 1Oμm DFR
DFR L/S=40/20
After Etching----> 30/30
E/F=S.0~6.0

L/5=30/30
18μm Cu, 15μm DFR
DFR L/S=40/20
After Etching----> 30/30
E/F=4.0~4.5

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